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Pixelated Low Gain Avalanche Detectors

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Outline

- Introduction:
 - Avalanche PhotoDiodes (APDs)
- Low Gain Avalanche Detector (LGAD)
 - From pads to pixels
 - Proposed double-sided sensor
 - Simulated performance
- CMOS Avalanche PhotoDiodes
 - Experimental results for standard 0.15 μ m CMOS
 - Gain and noise modeling
- Conclusions







Avalanche PhotoDiodes (APDs)

P-N junctions diodes specially made to exploit impact ionization effects



Linear mode: $V < V_{BD}$:

- Photo-current amplified by a factor M
- Output current proportional to the optical power

Geiger mode: V > V_{BD}:

- Digital photon counter
- Output signal stream with N pulses/s
- Core of SiPMs





Linear-Mode APDs applications

Linear-mode APDs are suitable for applications requiring **high bandwidth** and **high sensitivity**:

- Telecommunication receivers
- High speed laser scanners
- Time-resolved imaging (ToF ranging, FLIM)
- X γ rays, ionizing particles for biomedical and physics applications (w and w/o scintillators)





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Linear-mode APDs Figures of Merit

- Quantum Efficiency
- Excess noise factor
- Gain-Bandwidth product
- Dark current
- Breakdown voltage
- Temperature sensitivity
- Breakdown voltage uniformity
- Avalanche gain uniformity

Pixel Arrays





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IEEE Trans. Electron Devices 13 (1966) 164





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Low Gain Avalanche Detector (LGAD)



• APDs revisited for ionizing particles

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- Aiming at low gain both before and after irradiation
- Gain vs breakdown voltage trade-off
- High sensitivity to the implant dose of the multiplication layer
- JTE to prevent from edge breakdown



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G. Pellegrini, et al., HSTD9 (2013)

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From pads to pixels

Possible segmentation options in electron multiplying structures





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Not a completely new problem ...



- APD arrays for fast X-ray hybrid pixel detectors
- Special technology developed by Excelitas Canada Inc.
- Thickness 120 μm and 200 $\mu m,$ gain ~ 100 @ Vbias = 500V
- Large gain non uniformity ±15%

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C. Thil et al., 2012 IEEE NSS, N1-231





- Pixel side is simple, gain side quite complex (4 doping steps)
- Plan: start from thick 6" wafers (275 μ m) before going thinner (100 μ m)
- TCAD simulations to predict the performance

G.F. Dalla Betta, RESMDD 2014



TCAD (1): Electrical parameters



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- Simulation results scaled to 50x50 μm² pixels
- Strong impact of the B dose on the breakdown voltage
- Comparison at similar breakdown voltage
- Two-phase depletion behavior observed in both C-V and I-V





- Simulated with mip (Heavy Ion Model) in cylindrical coordinates
- Gain defined as ratio of integral charge with/without avalanche
- Similar gain at high voltage (~15) but with quite different trend

Excess noise factor can be fit with:

$$F = M \cdot k + \left(2 - \frac{1}{M}\right) \cdot (1 - k)$$

k= α_p / α_n – ionization ratio

R.J. McIntyre, IEEE TED 13 (1966) 164

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TCAD (3): Signals



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- Current pulses in response to a mip (cylindrical coordinates) at different voltages
- Pulse duration dominated by drift of • multiplied holes, thus proportional to the substrate thickness

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Impact of segmentation (weighting field): significant delay for 275 µm, much smaller for 100 μ m





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Going one step further



- Fast timing circuits might be difficult to embed in small pixels
- But different functions could be divided between the two sides:
 - Position measurement from the small pixel side
 - Time measurement from the gain side \rightarrow capacitance is an issue
- Segmentation of the gain side (macro pixels, ~1mm², ~1pF)







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Segmentation of the gain side



• Same technology, different layout

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- Acceptable efficiency reduction from macro-pixel edges (~5%)
- It can work safely up to >1200V before breakdown





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APD integration in CMOS

- Significant results in the past ten years
- Mainly driven by telecom receivers, but increasing interest also for imaging
- Advantages:
 - Integrated electronics: low parasitics, low costs
 - Array fabrication possible
- Challenges:
 - Guard ring fabrication
 - Doping profiles not optimized for low noise and high quantum efficiency



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STI







metal shield

STI



Multiplication gain, M





 V_{B} = 23.1 V, σ = 260mV







Quantum Efficiency



Better in the UV and blue



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Better in the NIR







• UV light: electron-initiated avalanche

p-sub

NIR light: mixed – majority of hole injection



	pwell/niso	metal shield
poly-	Si	
nwell	p+	STI
n-iso		
p-sub		

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- UV light: electron-initiated avalanche
- NIR light: mixed majority of electron injection









- Local model not suitable due to high electric field and narrow space-charge regions
- Very good agreement with non-local models for electron-initiated avalanche





Ila Betta Munich, Feb. 13, 2015 **F vs M: non-local model**



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	pwell/niso	metal shield
poly	-Si	_
n+ nwell	p+	STI
n-iso		
p-sub		

- Also non-local model with hole-initiated avalanche overestimates F
- Good agreement with NIR approximation (mixed injection) with Xj as a fitting parameter





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Conclusions

- 1) Design options for pixelated LGADs were reported
 - TCAD simulations have been used to predict the sensor performance with encouraging results
- 2) Low-noise APDs can be integrated in CMOS processes
 - Good uniformity \rightarrow Arrays are feasible
 - Non-local ionization models can yield an accurate excess noise predictions

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